

**MAPC-A2025** 

Rev. V1

#### **Features**

- MACOM PURE CARBIDE™ Amplifier Series
- Optimized for 3.3 4.2 GHz Applications
- High Terminal Impedances for Broadband Performance
- 26 36 V Operation
- Low Thermal Resistance
- 100% RF Tested
- RoHS\* Compliant

#### **Applications**

- 5G Cellular Networks
- Tri-band Small Cells

## **Description**

The MAPC-A2025 is a GaN on Silicon Carbide HEMT D-mode amplifier suitable for applications 1W average power and optimized for 3.3 - 4.2 GHz modulated signal operation. The device supports pulsed, and linear operation with peak output power levels to 8 W (39 dBm) in an 4 mm surface mount QFN package.

## **Typical Doherty Performance:**

 WCDMA 3GPP TM1, 10 dB PAR @ 0.01% CCDF. V<sub>DS</sub> = 32 V, I<sub>DQ</sub> = 60 mA, T<sub>C</sub> = 25°C, P<sub>OUT</sub> = 32 dBm

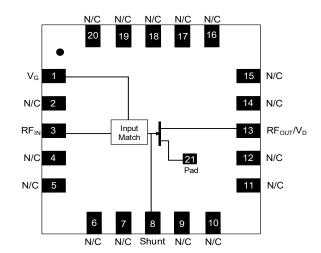
Frequency (GHz)	GP (dB)	η <sub>D</sub> (%)	Output PAR (dB)	ACPR (dBc)
3.3	16.3	36	6.8	-33.3
3.6	16.0	32	7.6	-37.1
3.9	16.4	32	7.6	-37.3
4.2	16.5	35	6.9	-32.9

#### **Ordering Information**

Part Number	Package
MAPC-A2025-AQ000	Bulk Quantity
MAPC-A2025-AQTR1	Tape and Reel
MAPC-A2025-AQSB1	Sample Board



#### **Functional Schematic**



## **Pin Configuration**

Pin#	Pin Name	Function
1	$V_{G}$	Gate Voltage
2, 4-7, 9-12, 14-20	N/C	Not Connected
3	RF <sub>IN</sub>	RF Input
8	SHUNT	Gate Shunt Capacitor
13	RF <sub>OUT</sub> / V <sub>D</sub>	RF Output / Drain Voltage
21	Pad <sup>1</sup>	Ground / Source

The pad on the package bottom must be connected to RF, DC and thermal ground.

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<sup>\*</sup> Restrictions on Hazardous Substances, compliant to current RoHS EU directive.



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## RF Electrical Characteristics: $T_C = 25^{\circ}C$ , $V_{DS} = 32 \text{ V}$ , $I_{DQ} = 60 \text{ mA}$ Note: Performance in MACOM Single-ended Class-AB Evaluation Circuit, 50 $\Omega$ system.

Parameter	Test Conditions	Symbol	Min.	Тур.	Max.	Units
Small Signal Gain	Pulsed <sup>2</sup> , 4.2 GHz	G <sub>SS</sub>	-	18.0	-	dB
Saturated Output Power	Pulsed <sup>2</sup> , 4.2 GHz	P <sub>SAT</sub>	-	38.0	-	dBm
Drain Efficiency at Saturation	Pulsed <sup>2</sup> , 4.2 GHz	η <sub>SAT</sub>	-	59	-	%
Modulated Peak Power	WCDMA <sup>3</sup> , 4.2 GHz	P2.5dB <sup>4</sup>	-	38.7	-	dBm
Gain Flatness in 60MHz	WCDMA <sup>3</sup> , P <sub>OUT</sub> = 32 dBm	G <sub>F</sub>	-	0.1	-	dB
Gain Variation (-25°C to +105°C)	WCDMA <sup>3</sup> , 4.2 GHz, $P_{OUT} = 32 \text{ dBm}$	ΔG	1	0.013	-	dB/°C
Power Variation (-25°C to +105°C)	Pulsed <sup>2</sup> , 4.2 GHz	Δ P2.5dB	-	0.006	-	dBm/°C
Power Gain	WCDMA <sup>3</sup> , 4.2 GHz, $P_{OUT}$ = 32 dBm	G <sub>P</sub>	-	16.5	-	dB
Drain Efficiency	WCDMA <sup>3</sup> , 4.2 GHz, P <sub>OUT</sub> = 32 dBm	η	-	35	-	%
Output CCDF @ 0.01%	WCDMA <sup>3</sup> , 4.2 GHz, P <sub>OUT</sub> = 32 dBm	PAR	-	6.9	-	dB
Adjacent Channel Power	WCDMA <sup>3</sup> , 4.2 GHz, P <sub>OUT</sub> = 32 dBm	ACP	-	-32.9	-	dBc
Input Return Loss	WCDMA <sup>3</sup> , 4.2 GHz, P <sub>OUT</sub> = 32 dBm	IRL	-	-9	-	dB
Ruggedness: Output Mismatch	All phase angles	Ψ	VSWR	= 10:1, No	Device D	Damage

Pulse details: 100 µs pulse width, 1 ms period, 10% Duty Cycle

## RF Electrical Characteristics: $T_A = 25$ °C, $V_{DS} = 32$ V, $I_{DQ} = 60$ mA Note: Performance in MACOM Single-ended Class-AB Production Test Fixture, 50 $\Omega$ system.

Parameter	Test Conditions	Symbol	Min.	Тур.	Max.	Units
Power Gain	WCDMA <sup>3</sup> , 4.2 GHz, P <sub>OUT</sub> = 33 dBm	$G_{P}$	13.0	13.9	1	dB
Drain Efficiency	WCDMA <sup>3</sup> , 4.2 GHz, P <sub>OUT</sub> = 33 dBm	η	21.5	25.0	-	%
Output CCDF @ 0.01%	WCDMA <sup>3</sup> , 4.2 GHz, P <sub>OUT</sub> = 33 dBm	PAR	7.0	7.4	-	dB
Input Return Loss	WCDMA <sup>3</sup> , 4.2 GHz, P <sub>OUT</sub> = 33 dBm	IRL	ı	-13.3	ı	dB

## DC Electrical Characteristics: T<sub>c</sub> = 25°C

Parameter	Test Conditions	Symbol	Min.	Тур.	Max.	Units
Drain-Source Leakage Current	$V_{GS} = -8 \text{ V}, V_{DS} = 100 \text{ V}$	I <sub>DLK</sub>	-	-	1.4	mA
Gate-Source Leakage Current	$V_{GS}$ = -8 V, $V_{DS}$ = 0 V	$I_{GLK}$	-	-	-1.4	mA
Gate Threshold Voltage	$V_{DS} = 32 \text{ V}, I_{D} = 1.4 \text{ mA}$	$V_T$	-	-2.9	-	V
Gate Quiescent Voltage	$V_{DS} = 32 \text{ V}, I_{D} = 60 \text{ mA}$	$V_{GSQ}$	-	-2.4	-	V
Maximum Drain Current	V <sub>DS</sub> = 7 V, pulse width 300 μs	I <sub>D, MAX</sub>	-	1.2	-	Α

Modulated Signal: 3.84MHz, WCDMA 3GPP TM1 64 DPCH, 9.9 dB PAR @ 0.01% CCDF P2.5dB = P<sub>OUT</sub> + 7.5 dB where P<sub>OUT</sub> is the average output power measured using a modulated signal<sup>5</sup> where the output PAR is compressed to 7.5 dB @ 0.01% probability CCDF.



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## Absolute Maximum Ratings<sup>5,6,7,8.9</sup>

Parameter	Absolute Maximum		
Drain Source Voltage, V <sub>DS</sub>	100 V		
Gate Source Voltage, V <sub>GS</sub>	-10 to 3 V		
Gate Current, I <sub>G</sub>	1.4 mA		
Storage Temperature Range	-65°C to +150°C		
Case Operating Temperature Range	-40°C to +120°C		
Channel Operating Temperature Range, T <sub>CH</sub>	-40°C to +225°C		
Absolute Maximum Channel Temperature	+250°C		

- Exceeding any one or combination of these limits may cause permanent damage to this device.

- MACOM does not recommend sustained operation above maximum operating conditions. Operating at drain source voltage  $V_{DS} < 36 \text{ V}$  will ensure MTTF > 2.51 x  $10^6$  hours. Operating at nominal conditions with  $T_{CH} \le 225^{\circ}\text{C}$  will ensure MTTF > 2.51 x  $10^6$  hours. MTTF may be estimated by the expression MTTF (hours) = A  $e^{[B+C/(T+273)]}$  where T is the channel temperature in degrees Celsius., A = 1.93, B = -45.31, and C = 29,585.

## Thermal Characteristics<sup>10</sup>

Parameter	Test Conditions	Symbol	Typical	Units
Thermal Resistance using Finite Element Analysis	V <sub>DS</sub> = 32 V T <sub>C</sub> = 85°C, T <sub>CH</sub> = 225°C	$R_{\theta}(FEA)$	14.7	°C/W

<sup>10.</sup> Case temperature measured using thermocouple embedded in heat-sink. Contact local applications support team for more details on this measurement.

#### **Handling Procedures**

Please observe the following precautions to avoid damage:

### Static Sensitivity

Gallium Nitride Circuits are sensitive to electrostatic discharge (ESD) and can be damaged by static electricity. Proper ESD control techniques should be used when handling these devices.



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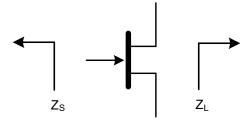
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## Pulsed<sup>2</sup> Load-Pull Performance Reference Plane at Device Leads

		Maximum Output Power					
			$V_{DS} = 32$	$V, I_{DQ} = 48 \text{ mA}$	, T <sub>C</sub> = 25°C, P	2.5dB	
Frequency (GHz)	Z <sub>SOURCE</sub> (Ω)	Z <sub>LOAD</sub> <sup>11</sup> (Ω)	Gain (dB)	P <sub>OUT</sub> (dBm)	P <sub>OUT</sub> (W)	η <sub>□</sub> (%)	AM/PM (°)
3.3	94.6 - j10.5	34.9 + j8.9	14.6	39.3	8.5	47.4	-50.9
3.7	58.0 + j27.5	32.3 + j8.3	14.5	38.9	7.8	49.5	-89.4
4.0	34.1 + j24.3	25.1 + j7.0	15.0	39.2	8.3	53.9	-100.5
4.2	31.1 + j17.3	23.9 + j3.4	14.9	38.9	7.8	49.8	-112.6

		Maximum Drain Efficiency  V <sub>DS</sub> = 32 V, I <sub>DQ</sub> = 48 mA, T <sub>C</sub> = 25°C, P2.5dB					
			$V_{DS} = 32$	$V, I_{DQ} = 48 \text{ mA}$	, T <sub>C</sub> = 25°C, P	2.5dB	
Frequency (GHz)	Z <sub>SOURCE</sub> (Ω)	Z <sub>LOAD</sub> <sup>12</sup> (Ω)	Gain (dB)	P <sub>OUT</sub> (dBm)	P <sub>OUT</sub> (W)	η <sub>□</sub> (%)	AM/PM (°)
3.3	82.4 + j23.7	24.4 + j24.4	16.0	38.0	6.3	54.1	-62.8
3.7	43.4 + j31.9	22.3 + j19.1	16.0	38.1	6.5	53.6	-89.4
4.0	24.3 + j20.2	18.0 + j14.0	16.2	38.6	7.2	59.2	-109.7
4.2	23.9 + j11.9	18.1 + j11.5	16.0	38.4	6.9	55.5	-124.3

#### Impedance Reference



Z<sub>SOURCE</sub> = Measured impedance presented to the input of the device at package reference plane.

- 11. Load Impedance for optimum output power.
- 12. Load Impedance for optimum efficiency.

 $Z_{\text{LOAD}}$  = Measured impedance presented to the output of the device at package reference plane.

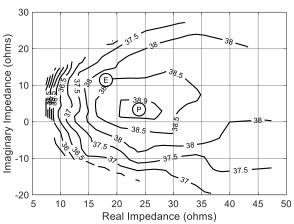


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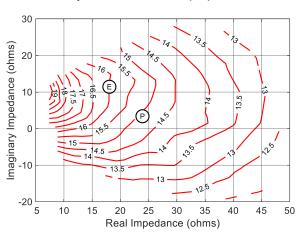
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## Pulsed<sup>2</sup> Load-Pull Performance 4.2GHz

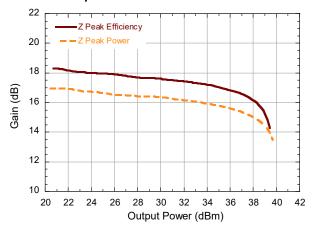
#### P2.5dB Loadpull Output Power Contours (dBm)



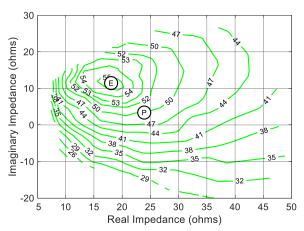
#### P2.5dB Loadpull Gain Contours (dB)



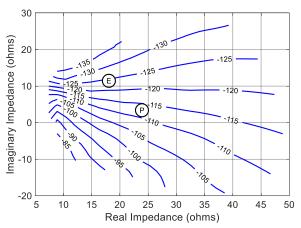
#### Gain vs. Output Power



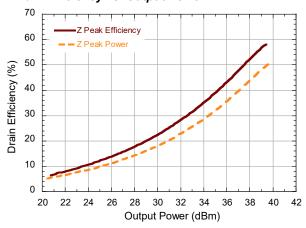
#### P2.5dB Loadpull Drain Efficiency Contours (%)



#### P2.5dB Loadpull AM/PM Contours (°)



#### Drain Efficiency vs. Output Power

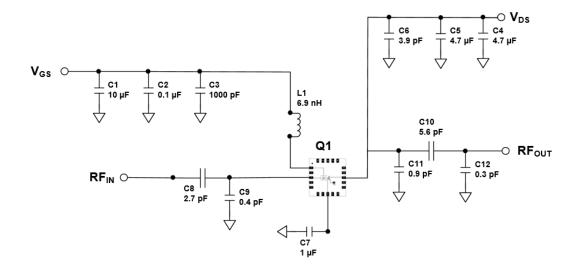




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## Evaluation Test Fixture and Recommended Tuning Solution 3.3 - 4.2 GHz



#### **Description**

Parts measured on evaluation board (20-mil thick RO4350). Matching is provided using a combination of lumped elements and transmission lines as shown in the simplified schematic above. Recommended tuning solution component placement, transmission lines, and details are shown on the next page.

## Bias Sequencing Turning the device ON

- 1. Set V<sub>GS</sub> to pinch-off (V<sub>P</sub>).
- 2. Turn on V<sub>DS</sub> to nominal voltage (32 V).
- 3. Increase  $V_{\text{GS}}$  until  $I_{\text{DS}}$  current is reached.
- 4. Apply RF power to desired level.

#### **Turning the device OFF**

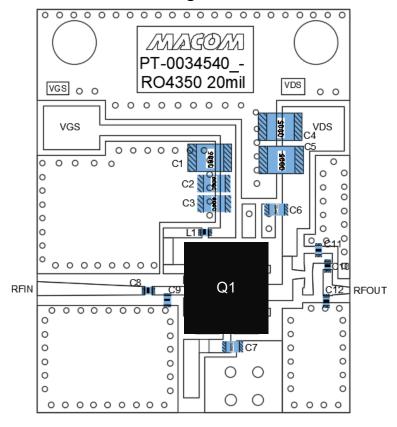
- 1. Turn the RF power OFF.
- 2. Decrease  $V_{GS}$  down to  $V_P$  pinch-off.
- 3. Decrease V<sub>DS</sub> down to 0 V.
- 4. Turn off V<sub>GS</sub>.



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## Evaluation Board and Recommended Tuning Solution 3.3 - 4.2 GHz



Reference Designator	Value	Tolerance	Manufacturer	Part Number		
C1	10 µF	+/- 20%	TDK Corporation	C2012X5R1C106M085AC		
C2	0.1 μF	+/- 10%	Murata	GCM21BR72A104KA37L		
C3	1000 pF	+/- 5%	Murata	GRM1555C1H102JA01D		
C4, C5	4.7 μF	+/- 10%	Murata	GRM21BC81H475KE11L		
C6	3.9 pF	+/- 0.05pF	Murata	GQM1555C2D3R9WB01D		
C7	1 μF	+/- 10%	Murata	GRM155Z71A105KE01D		
C8	2.7 pF	+/- 0.05 pF	Murata	GQM0335C2D2R7WB01D		
C9	0.4 pF	+/- 5%	Murata	GQM0335C2DR40WB01D		
C10	5.6 pF	+/- 10%	Murata	GQM0335C2D5R6WB01D		
C11	0.9 pF	+/- 5%	Murata	GQM0335C2DR90WB01D		
C12	0.3 pF	+/- 5%	Murata	GQM0335C2DR30WB01D		
L1	6.9 nH	+/- 10%	Coilcraft	0201DS-6N9XJE		
Q1			MACOM	MAPC-A2025		
PCB	RO4350, 20 mil, 1 oz Cu, Tin Lead Finish					

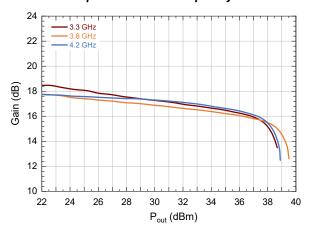


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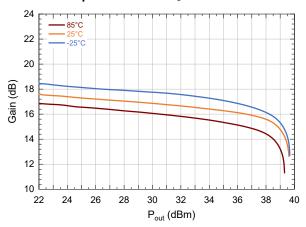
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Typical Performance Curves as Measured in the 3.3 - 4.2 GHz Evaluation Board: Pulsed<sup>2</sup> 3.8 GHz,  $V_{DS}$  = 32 V,  $I_{DQ}$  = 60 mA,  $T_{C}$  = 25°C

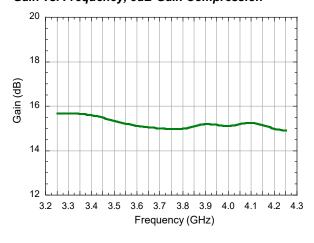
Gain vs. Output Power and Frequency



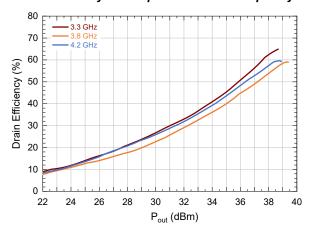
Gain vs. Output Power and Tc



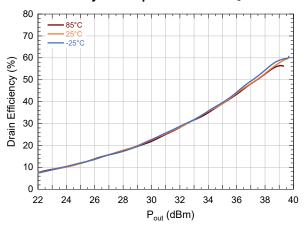
Gain vs. Frequency, 3dB Gain Compression



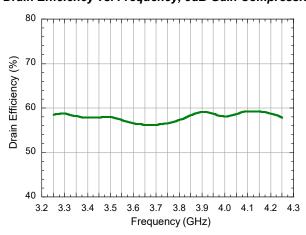
Drain Efficiency vs. Output Power and Frequency



Drain Efficiency vs. Output Power and T<sub>C</sub>



Drain Efficiency vs. Frequency, 3dB Gain Compression



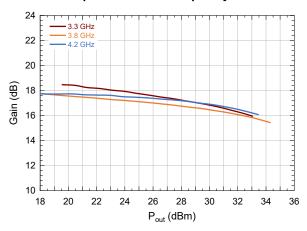


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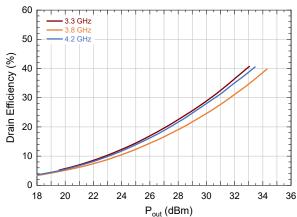
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Typical Performance as Measured in the 3.3 - 4.2 GHz Evaluation Board: WCDMA 3GPP TM1 64 DPCH 9.9 dB PAR @ 0.01% CCDF,  $V_{DS}$  = 32 V,  $I_{DQ}$  = 60 mA,  $T_{C}$  = 25 °C

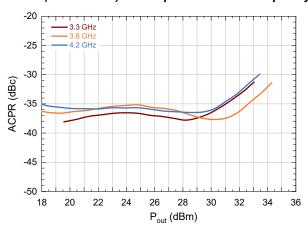
Gain vs. Output Power and Frequency



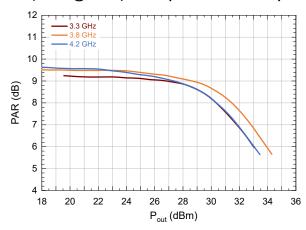
Drain Efficiency vs. Output Power and Frequency



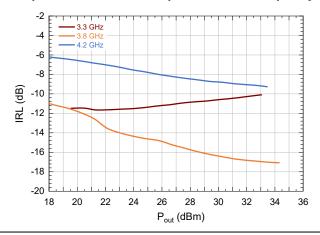
ACPR (Max ±5 MHz) vs. Output Power and Frequency



PAR (CCDF @ 0.01%) vs. Output Power and Frequency



Input Return Loss vs. Output Power and Frequency



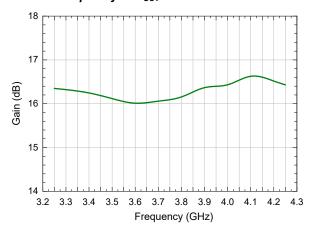


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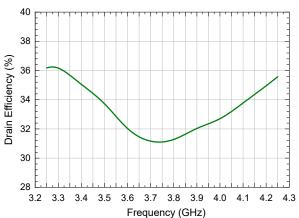
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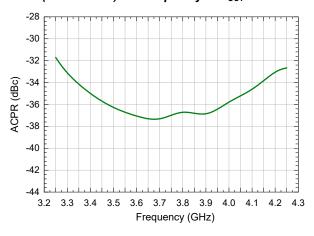
Gain vs. Frequency at  $P_{OUT} = 32 \text{ dBm}$ 



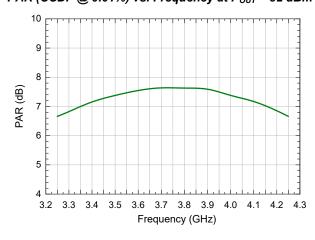
## Drain Efficiency vs. Frequency at $P_{OUT} = 32 \text{ dBm}$



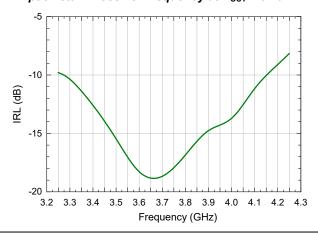
ACPR (Max  $\pm 5$  MHz) vs. Frequency at  $P_{OUT} = 32$  dBm



PAR (CCDF @ 0.01%) vs. Frequency at P<sub>OUT</sub> = 32 dBm



Input Return Loss vs. Frequency at  $P_{OUT} = 32 \text{ dBm}$ 

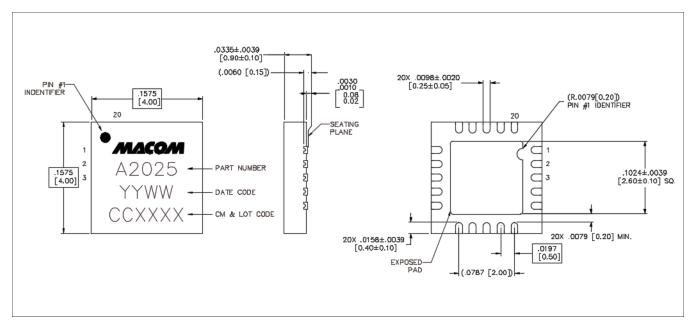




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## Lead-Free 4 mm 20-Lead Package Dimensions<sup>†</sup>



<sup>&</sup>lt;sup>†</sup> Reference Application Note AN0004363 for lead-free solder reflow recommendations. Meets JEDEC moisture sensitivity level 3 requirements. Plating is NiPdAu

# GaN Amplifier 32 V, 8 W 3.3 - 4.2 GHz



## MACOM PURE CARBIDE

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